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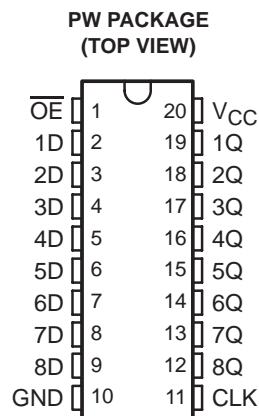
## SN74LVTH574-EP

### 3.3-V ABT OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )**
- **Supports Unregulated Battery Operation Down To 2.7 V**
- **Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$**
- **$I_{off}$  and Power-Up 3-State Support Hot Insertion**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



#### description/ordering information

This octal flip-flop is designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The eight flip-flops of the SN74LVTH574 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – PW Tape and reel	SN74LVTH574IPWREP	LH574EP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**WITH 3-STATE OUTPUTS**

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**description/ordering information (continued)**

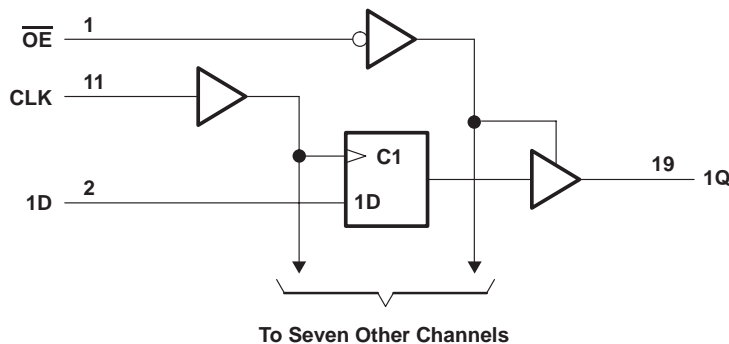
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

**FUNCTION TABLE**  
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	$Q_0$
H	X	X	Z

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$	-0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state, $V_O$ (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, $I_O$	128 mA
Current into any output in the high state, $I_O$ (see Note 2)	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	83°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

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### recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2.7	3.6	V
V <sub>IH</sub>	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
V <sub>I</sub>	Input voltage		5.5	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10 ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate	200		μs/V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V <sub>IK</sub>		V <sub>CC</sub> = 2.7 V,	I <sub>I</sub> = -18 mA			-1.2	V
V <sub>OH</sub>		V <sub>CC</sub> = 2.7 V to 3.6 V,	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0.2			V
		V <sub>CC</sub> = 2.7 V,	I <sub>OH</sub> = -8 mA	2.4			
		V <sub>CC</sub> = 3 V,	I <sub>OH</sub> = -32 mA	2			
V <sub>OL</sub>		V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 100 μA			0.2	V
			I <sub>OL</sub> = 24 mA			0.5	
		V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 16 mA			0.4	
			I <sub>OL</sub> = 32 mA			0.5	
			I <sub>OL</sub> = 64 mA			0.55	
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = 0 or 3.6 V,	V <sub>I</sub> = 5.5 V			10	μA
		V <sub>CC</sub> = 3.6 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1	
	Data inputs	V <sub>CC</sub> = 3.6 V	V <sub>I</sub> = V <sub>CC</sub>			1	
			V <sub>I</sub> = 0			-5	
I <sub>off</sub>		V <sub>CC</sub> = 0,	V <sub>I</sub> or V <sub>O</sub> = 0 to 4.5 V			±100	μA
I <sub>I</sub> (hold)	Data inputs	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 0.8 V			75	μA
			V <sub>I</sub> = 2 V			-75	
		V <sub>CC</sub> = 3.6 V‡,	V <sub>I</sub> = 0 to 3.6 V			±500	
I <sub>OZH</sub>		V <sub>CC</sub> = 3.6 V,	V <sub>O</sub> = 3 V			5	μA
I <sub>OZL</sub>		V <sub>CC</sub> = 3.6 V,	V <sub>O</sub> = 0.5 V			-5	μA
I <sub>OZPU</sub>		V <sub>CC</sub> = 0 to 1.5 V, V <sub>O</sub> = 0.5 V to 3 V, $\overline{OE}$ = don't care				±100	μA
I <sub>OZPD</sub>		V <sub>CC</sub> = 1.5 V to 0, V <sub>O</sub> = 0.5 V to 3 V, $\overline{OE}$ = don't care				±100	μA
I <sub>CC</sub>		V <sub>CC</sub> = 3.6 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high			0.19	mA
			Outputs low			5	
			Outputs disabled			0.19	
ΔI <sub>CC</sub> §		V <sub>CC</sub> = 3 V to 3.6 V, One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND				0.2	mA
C <sub>i</sub>		V <sub>I</sub> = 3 V or 0				3	pF
C <sub>o</sub>		V <sub>O</sub> = 3 V or 0				7	pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

	V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		UNIT
	MIN	MAX	MIN	MAX	
f <sub>clock</sub> Clock frequency	150		150		MHz
t <sub>w</sub> Pulse duration, CLK high or low	3.3		3.3		ns
t <sub>su</sub> Setup time, data before CLK↑	2		2.4		ns
t <sub>h</sub> Hold time, data after CLK↑	0.3		0		ns

switching characteristics over recommended free-air temperature, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

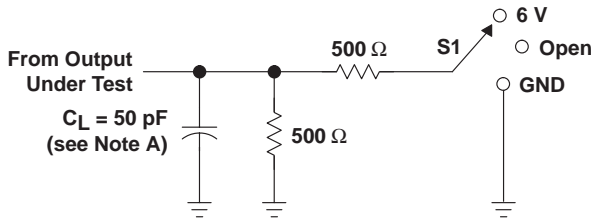
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
f <sub>max</sub>			150			150		MHz
t <sub>PLH</sub>	CLK	Q	1.8	3	4.5	5.3		ns
t <sub>PHL</sub>			1.8	3	4.5	5.3		
t <sub>PZH</sub>	$\overline{OE}$	Q	1.5	3.2	4.8	5.9		ns
t <sub>PZL</sub>			1.5	3.5	4.8	5.9		
t <sub>PHZ</sub>	$\overline{OE}$	Q	2	3.5	4.8	5.1		ns
t <sub>PLZ</sub>			2	3.2	4.4	4.4		

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

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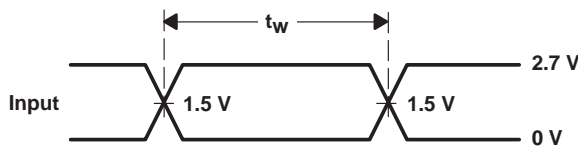
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**PARAMETER MEASUREMENT INFORMATION**

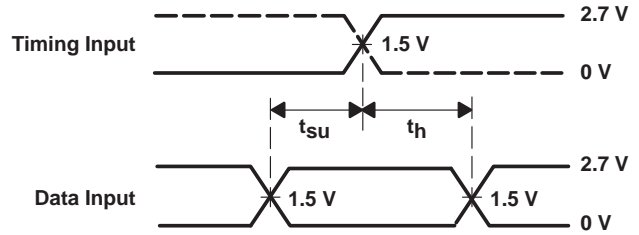


**LOAD CIRCUIT**

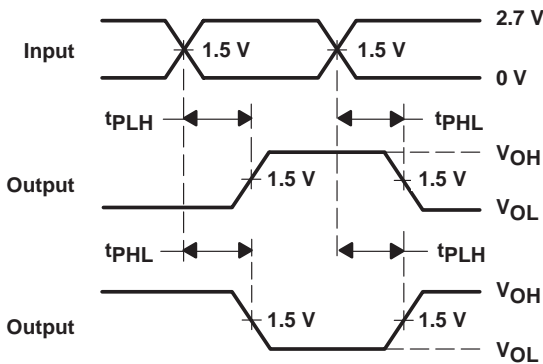
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



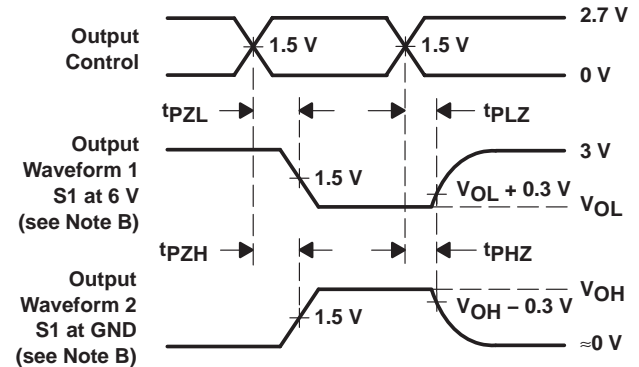
**VOLTAGE WAVEFORMS**  
**PULSE DURATION**



**VOLTAGE WAVEFORMS**  
**SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS**  
**PROPAGATION DELAY TIMES**  
**INVERTING AND NONINVERTING OUTPUTS**





**VOLTAGE WAVEFORMS**  
**ENABLE AND DISABLE TIMES**  
**LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVTH574IPWREP	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH574EP	
V62/04679-01XE	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH574EP	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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● Catalog: [SN74LVTH574](#)

● Military: [SN54LVTH574](#)

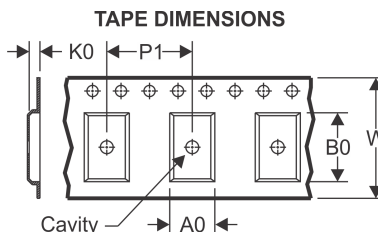
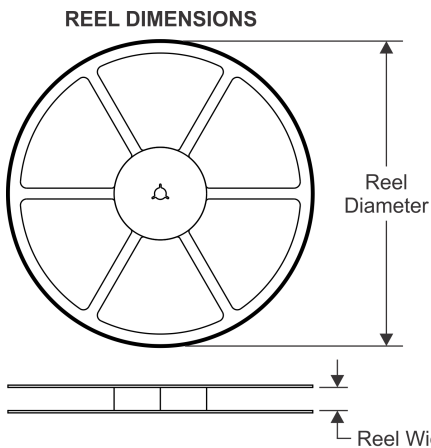
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● Military - QML certified for Military and Defense Applications

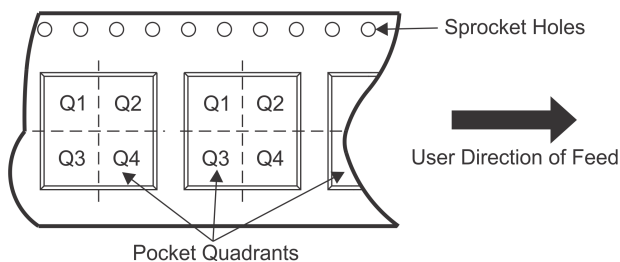


**TAPE AND REEL INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

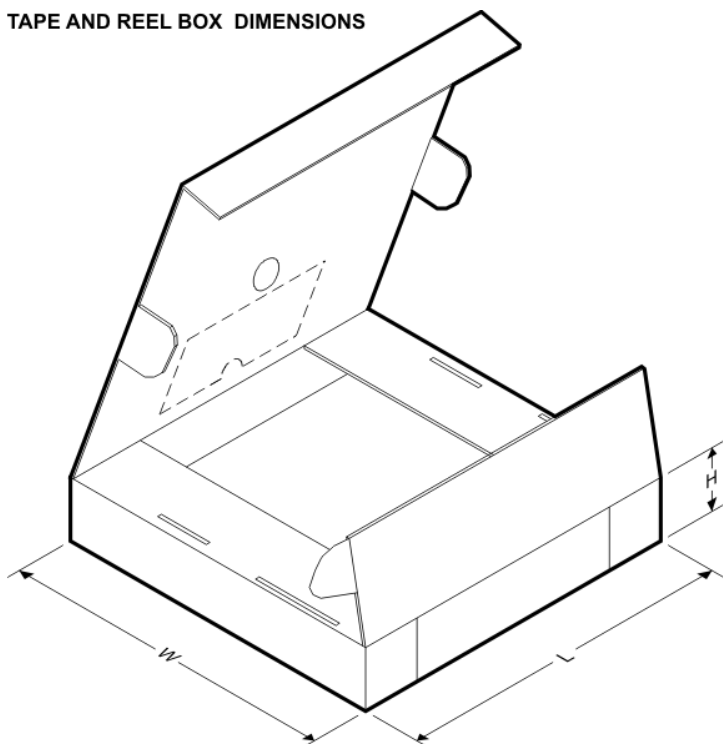
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH574IPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH574IPWREP	TSSOP	PW	20	2000	367.0	367.0	38.0

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
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Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>		
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>	<b>TI E2E Community</b>	<a href="http://e2e.ti.com">e2e.ti.com</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>		